

TEST CERTIFICATE

FROM :Semitech Materials Company

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GRADE : RP71T5 (HRT : Heat Release Tape)

No.	Item	Unit	Spec.	Measured Values	Result	Test Methods	
1	Base film Thickness(PET)	μm	100±2	100	OK	Digi-micrometer	
2	Release Film #1 Thickness(PET)	μm	36±2	36	OK		
3	Release Film #2 Thickness(PET)	μm	36±2	36	OK		
4	HRA #1 (Heat Release Adhesive Layer)	μm	45±2	45	OK		
5	HRA #2 (Heat Release Adhesive Layer)	μm	45±2	45	OK		
6	Total Thickness	μm	262±12	262	OK		
7	Adhesion at room temperature (25°C, PET 75)	Before Heat Peeling	gf/25mm	350±100	350	OK	KS T 1028 : 2009
		After Heat Peeling	gf/25mm	10 or less	0	OK	
8	Heat Release peeling (removal of copper foil)	-	Complete separation	OK	OK	145±5°C/10±1min (10cm x 10cm)	
9	Exterior (Dust,Bubble)	Defect < 2mm	Point /Meter	3 or less	0	OK	3M company with Flag tag
		2mm ≤ Defect		Zero	0	OK	
Guarantee		6 month					

Remark This technical specification data should not be copied and hand over to 3rd-party for any purpose.

Test Conditions 145°C 10min

